Product Change Notification

109442 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 109442 - 00

Change Title: Intel(R) Compute Module MFS5000SI, Intel(R) Compute Module MFS5520VI, PCN 109442-00, Product Material, Reduce the number, size and location of tooling holes on the compute module top covers.

Date of Publication: June 22, 2009

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jul 24, 2009

Description of Change to the Customer:

Reducing the number of tooling holes on the compute module top covers from four (4) to three (3). Changing the hole diameter from 8.05 mm to 5.05 mm and reconfiguring the location of the holes away from the configuration label. Holes are used in manufacturing of the top cover and a new tool requires fewer and smaller holes during the cutting and bending process. In addition, the holes are being moved so they are not covered by the configuration label allowing dust to stick to label adhesive showing through a hole.

Customer Impact of Change and Recommended Action:

This change will have no impact on system operation and no customer action is required.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Post Change Product Code	Post Change MM#	Post Change TA
MFS5000SI 900409	900409	D91952-00X	MFS5000SI	900409	D91952-00X
MFS5000SIB 900410	900410	E19099-00X	MFS5000SIB	900410	E19099-00X
MFS5520VI 901369	901369	E42643-00X	MFS5520VI	901369	E42643-00X
MFS5520VIB 901699	901699	E54314-00X	MFS5520VIB	901699	E54314-00X

Reference Documents / Attachments:

Document:	Location #:

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 22, 2009	00	Originally Published PCN